

Data sheet Product ICK BGA 25 x 25 x 14



Heatsinks and active heatsinks for processors>Heatsinks for BGAs

25 x 25 x 14 mm, for IC design BGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	25 mm
height:	14 mm
plate thickness:	1.8 mm
length:	25 mm
thermal resistance:	17 - 7.5 K/W
dissipation loss:	3.5 W
surface:	black anodised

Technical Drawing

